

## Silicon Carbide Power Schottky Diode

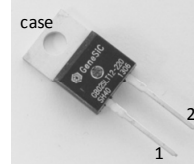
$V_{RRM}$	=	1200 V
$V_F$	=	1.45 V
$I_F$	=	2 A
$Q_C$	=	14 nC

### Features

- 1200 V Schottky rectifier
- 175 °C maximum operating temperature
- Temperature independent switching behavior
- Superior surge current capability
- Positive temperature coefficient of  $V_F$
- Extremely fast switching speeds
- Superior figure of merit  $Q_C/I_F$

### Package

- RoHS Compliant


**TO – 220AC**


### Advantages

- Improved circuit efficiency (Lower overall cost)
- Low switching losses
- Ease of paralleling devices without thermal runaway
- Smaller heat sink requirements
- Low reverse recovery current
- Low device capacitance
- Low reverse leakage current at operating temperature

### Applications

- Power Factor Correction (PFC)
- Switched-Mode Power Supply (SMPS)
- Solar Inverters
- Wind Turbine Inverters
- Motor Drives
- Induction Heating
- Uninterruptible Power Supply (UPS)
- High Voltage Multipliers

### Maximum Ratings at $T_j = 175\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Repetitive peak reverse voltage	$V_{RRM}$			1200		V
Continuous forward current	$I_F$	$T_C \leq 160\text{ °C}$		2		A
RMS forward current	$I_{F(RMS)}$	$T_C \leq 160\text{ °C}$		3		A
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	$T_C = 25\text{ °C}$ , $t_p = 10\text{ ms}$		18		A
		$T_C = 160\text{ °C}$ , $t_p = 10\text{ ms}$		15		A
Non-repetitive peak forward current	$I_{F,max}$	$T_C = 25\text{ °C}$ , $t_p = 10\text{ }\mu\text{s}$		100		A
$I^2t$ value	$\int i^2 dt$	$T_C = 25\text{ °C}$ , $t_p = 10\text{ ms}$		1.6		$A^2s$
		$T_C = 160\text{ °C}$ , $t_p = 10\text{ ms}$		1.1		$A^2s$
Power dissipation	$P_{tot}$	$T_C = 25\text{ °C}$		65		W
Operating and storage temperature	$T_j, T_{stg}$			-55 to 175		°C

### Electrical Characteristics at $T_j = 175\text{ °C}$ , unless otherwise specified

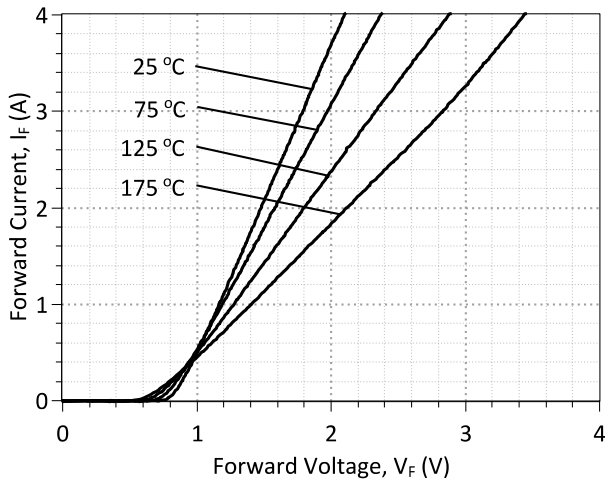
Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Diode forward voltage	$V_F$	$I_F = 2\text{ A}$ , $T_j = 25\text{ °C}$	1.35	1.45	1.75	V
		$I_F = 2\text{ A}$ , $T_j = 175\text{ °C}$		2.6	3.0	
Reverse current	$I_R$	$V_R = 1200\text{ V}$ , $T_j = 25\text{ °C}$	0.1	5	30	$\mu\text{A}$
		$V_R = 1200\text{ V}$ , $T_j = 175\text{ °C}$		10	100	
Total capacitive charge	$Q_C$	$I_F \leq I_{F,MAX}$ $di_F/dt = 200\text{ A}/\mu\text{s}$ $T_j = 175\text{ °C}$		$V_R = 400\text{ V}$	9	nC
	$V_R = 960\text{ V}$			14		
Switching time	$t_s$	$V_R = 1\text{ V}$ , $f = 1\text{ MHz}$ , $T_j = 25\text{ °C}$		$V_R = 400\text{ V}$	< 17	ns
				$V_R = 960\text{ V}$		
Total capacitance	C	$V_R = 1\text{ V}$ , $f = 1\text{ MHz}$ , $T_j = 25\text{ °C}$		131	pF	
		$V_R = 400\text{ V}$ , $f = 1\text{ MHz}$ , $T_j = 25\text{ °C}$		12		
		$V_R = 1000\text{ V}$ , $f = 1\text{ MHz}$ , $T_j = 25\text{ °C}$		8		

### Thermal Characteristics

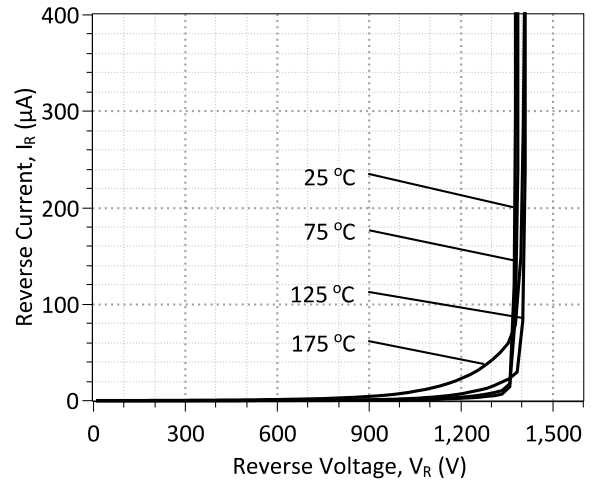
Thermal resistance, junction - case	$R_{thJC}$	2.3	°C/W
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### Mechanical Properties

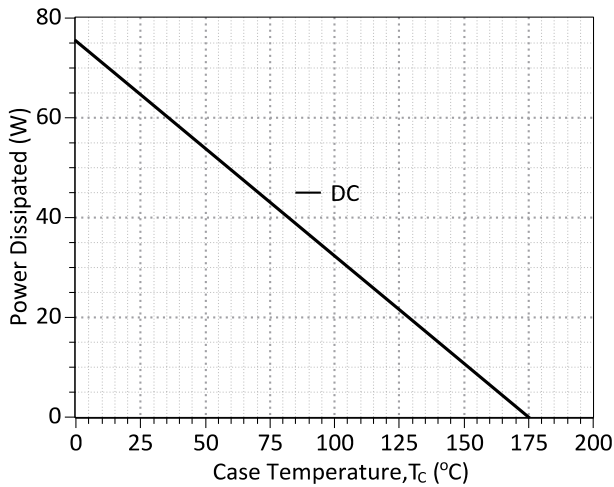
Mounting torque	M	0.6	Nm
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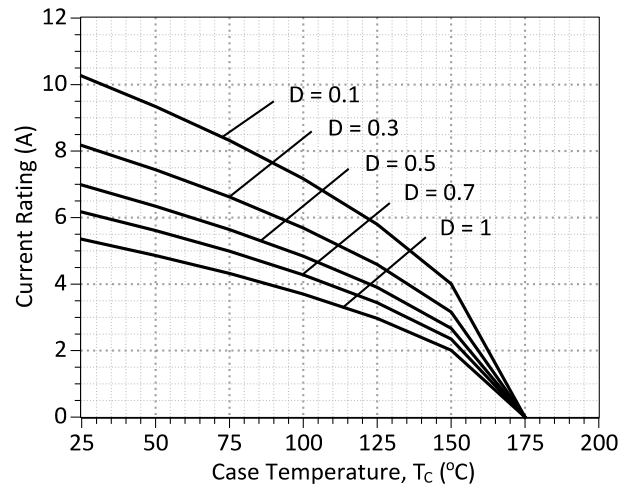
**Figure 1: Typical Forward Characteristics**



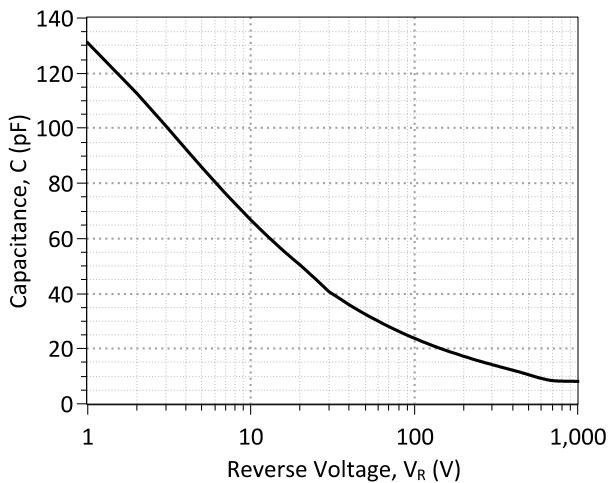
**Figure 2: Typical Reverse Characteristics**



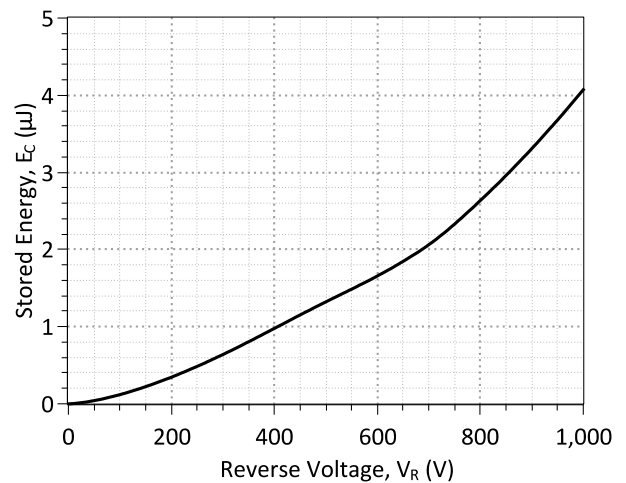
**Figure 3: Power Derating Curve**



**Figure 4: Current Derating Curves ( $D = t_p/T$ ,  $t_p = 400 \mu s$ )  
(Considering worst case  $Z_{th}$  conditions)**



**Figure 5: Typical Junction Capacitance vs Reverse Voltage Characteristics**



**Figure 6: Typical Switching Energy vs Reverse Voltage Characteristics**

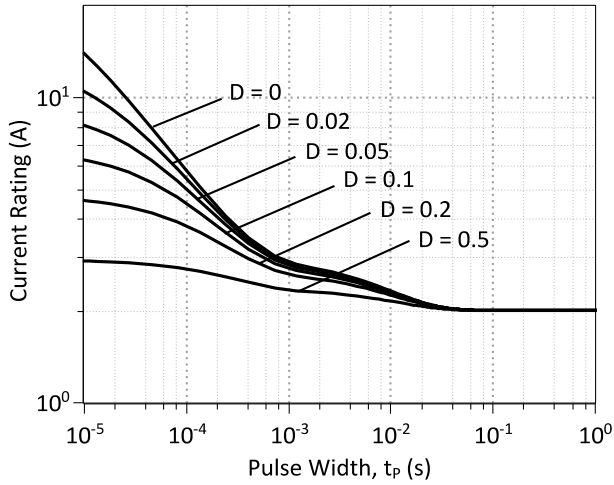


Figure 7: Current vs Pulse Duration Curves at  $T_c = 160\text{ }^\circ\text{C}$

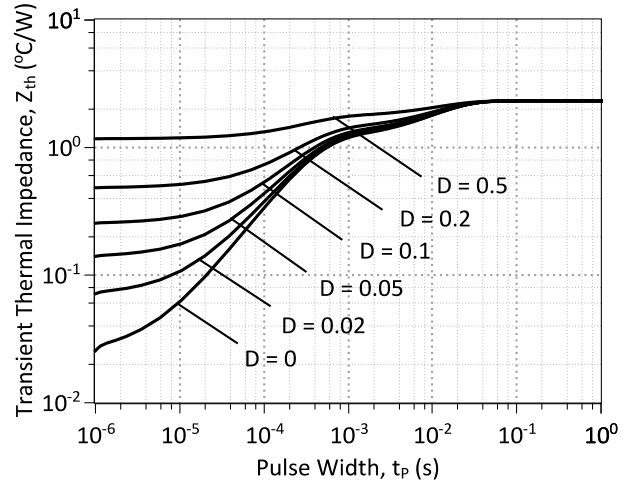
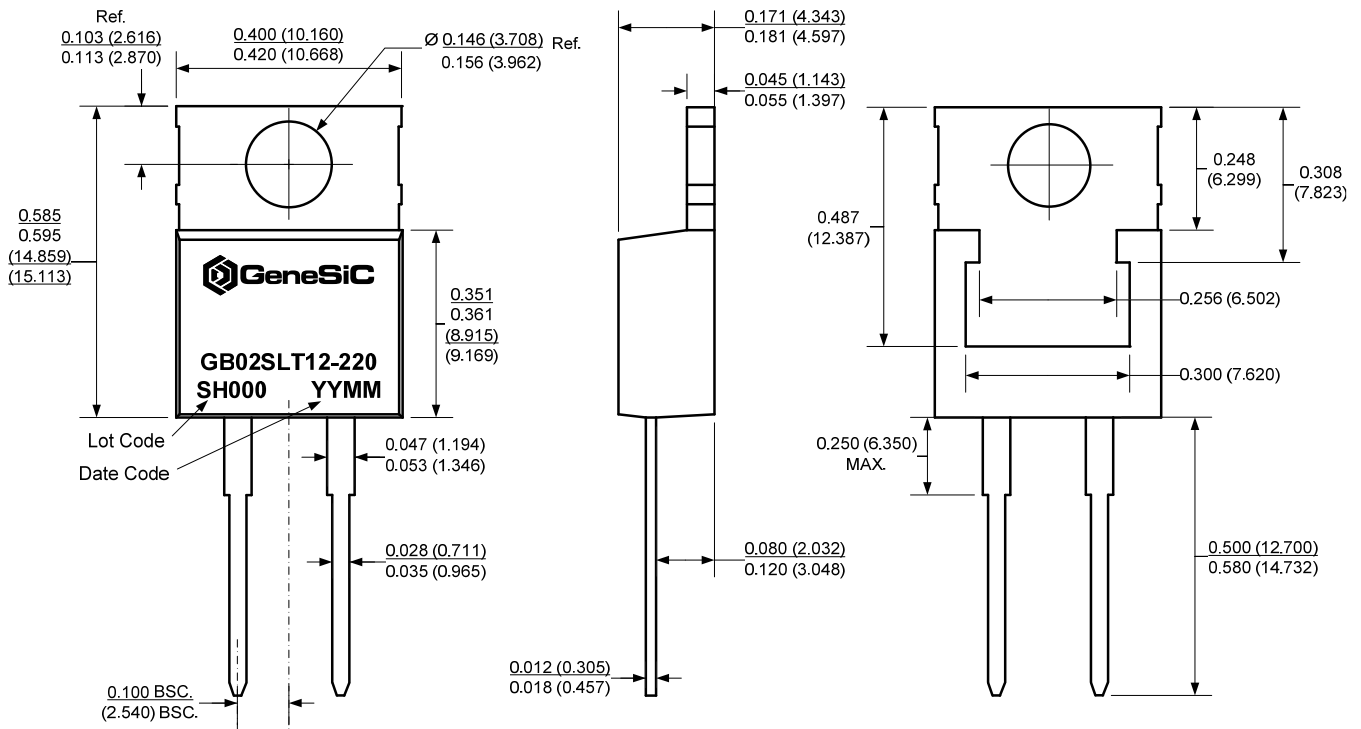


Figure 8: Transient Thermal Impedance

**Package Dimensions:**

**TO-220AC**

**PACKAGE OUTLINE**



**NOTE**  
 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.  
 2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

<b>Revision History</b>			
Date	Revision	Comments	Supersedes
2013/06/12	3	Updated Electrical Characteristics	
2012/12/18	2	Second generation update	
2012/05/22	1	Second generation release	
2010/12/13	0	Initial release	

## Published by

GeneSiC Semiconductor, Inc.  
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Dulles, VA 20166

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## SPICE Model Parameters

Copy the following code into a SPICE software program for simulation of the GB02SLT12-220 device.

```
*      MODEL OF GeneSiC Semiconductor Inc.
*
*      $Revision:   1.0           $
*      $Date:      04-SEP-2013   $
*
*      GeneSiC Semiconductor Inc.
*      43670 Trade Center Place Ste. 155
*      Dulles, VA 20166
*      http://www.genesicsemi.com/index.php/sic-products/schottky
*
*      COPYRIGHT (C) 2013 GeneSiC Semiconductor Inc.
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*
*      These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
*      OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
*      TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
*      PARTICULAR PURPOSE."
*      Models accurate up to 2 times rated drain current.
*
*      Start of GB02SLT12-220 SPICE Model
*
.SUBCKT GB02SLT12 ANODE KATHODE
R1 ANODE INT R=((TEMP-24)*0.0028); Temperature Dependant Resistor
D1 INT KATHODE GB02SLT12_25C; Call the 25C Diode Model
.MODEL GB02SLT12_25C D
+ IS      2.05E-15      RS      0.277
+ N       1            IKF     251
+ EG     1.2          XTI     -1.8
+ CJO    1.61E-10     VJ      0.4508
+ M      1.586        FC      0.5
+ TT     1.00E-10     BV      1500
+ IBV    1.00E-03     VPK     1200
+ IAVE   2            TYPE    SiC_Schottky
+ MFG    GeneSiC_Semiconductor
.ENDS
*
*      End of GB02SLT12-220 SPICE Model
```